

 ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES®		Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.		This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility. Adobe Reader version 7.0.5 is required to complete this declaration.					
1752-2 1.1		IPC Web Site for Information on IPC-1752 Standard http://www.ipc.org/IPC-175x			Form Type * Distribute		Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Informa		
Supplier Information									
Company Name * Mindspeed Technologies, Inc		Company Unique ID		Unique ID Authority		Response Date * 2011-09-15		Response Document ID	
Contact Name * Cynthia Ong		Title - Contact Program Manager		Phone - Contact * 949-579-5515		Email - Contact * cynthia.ong@mindspeed.com			
Authorized Representative * Amy Teng		Title - Representative Quality Engineer		Phone - Representative * 604-6328114		Email - Representative * amy.teng@mindspeed.com		Supplier Comments or URL for Additional Information	
	Requester Item Number	Mfr Item Number	Mfr Item Name	Effective Date	Version	Manufacturing Site	Weight *	UOM	Unit Type
	M21161G-25	M21161G-25	35HFCBGA 1156	2010-08-10	A	ASE, Taiwan	13,756.4	mg	EACH
	Alternate Recommendation		NA		Alternate Item Comments NA				
Manufacturing Process Information									
Terminal Plating / Grid Array Material SAC		Terminal Base Alloy N/A		J-STD-020 MSL Rating 5		Peak Process Body Temperature 245 C		Max Time at Peak Temperature 40 seconds	
Number of Reflow Cycles 3									
Comments NA									

Save the fields in this form to a file		Export Data		Import fields from a file into this form		Import Data		Locked	
RoHS Material Composition Declaration							Declaration Type *		Simplified
RoHS Directive 2002/95/EC		RoHS Definition: Quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material for Cadmium							
Supplier certifies that it gathered the information it provides in this form concerning RoHS restrictive substances using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part,the terms and conditions of that agreement, including any warranty rights and or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier s liability and the Company s remedies for issues that arise regarding information the Supplier provides in this form.									
RoHS Declaration *		4 - Item(s) does not contain RoHS restricted substances per the definition above except for selected exemptions					Supplier Acceptance *		Accepted
Exemptions: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.									
Exemption List Version		EL-2006/690/EC							
		15. Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit Flip Chip packages.							
Declaration Signature									
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.									
Supplier Digital Signature		Cynthia Ong		Digitally signed by Cynthia Ong DN: cn=Cynthia Ong, c=US, o=Mindspeed Technologies, Inc., email=cynthia.ong@mindspeed.com Date: 2011.09.27 18:58:20 -0700					

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Line Functions: +I Inserts a New Item /SubItem +M Inserts a new Material +C Inserts a new Substance Category +S Inserts a new Substance - Deletes the element line

	Item/SubItem Name		Homogeneous Material	Weight	Unit of Measure		Level	Substance Category		Substance	CAS	Exempt	Weight	Unit of Measure	Tolerance		PPM
															-	+	
	M21161G-25		Die	386.83	mg		C	GROUP-C		Silicon	7440-21-3	▼	386.83	mg			999,99
			Solder ball	1,018.09	mg		C	GROUP-C		Sn	7440-31-5	▼	982.4568	mg			964,99
							C	GROUP-C		Ag	7440-22-4	▼	30.5427	mg			30,000
							C	GROUP-C		Cu	7440-50-8	▼	5.09045	mg			5,000
			Underfill	42	mg		C	GROUP-C		Bisphenol F type liquid	9003-36-5	▼	8.4	mg			199,99
							C	GROUP-C		Silicon dioxide	60676-86-0	▼	19.32	mg			459,99
							C	GROUP-C		Bisphenol A type liquid	25068-38-6	▼	1.26	mg			29,999
							C	GROUP-C		Phenolic resin	9003-35-4	▼	8.4	mg			199,99
							C	GROUP-C		Additives	Trade Secret	▼	2.1	mg			49,999
							C	GROUP-C		Carbon black	1333-86-4	▼	0.42	mg			9,999.5
							C	GROUP-C		Amine type accelerator	Trade Secret	▼	2.1	mg			49,999
			Substrate	2,419.1	mg		B	Arsenic/Arsenic Comp		As	7440-38-2	▼	0.1	mg			7.2693
							C	GROUP-C		Polyphenylene ether (PF		▼	382	mg			157,90
							C	GROUP-C		Ag	7440-22-4	▼	2	mg			826.75
							C	GROUP-C		Epoxy resin		▼	51	mg			21,082
							C	GROUP-C		Talc	14807-96-6	▼	10	mg			4,133.7
							C	GROUP-C		BaSO4	7727-43-7	▼	12	mg			4,960.5
							C	GROUP-C		Cu	7440-50-8	▼	1,171	mg			484,06
							B	Bismuth/Bismuth Con		Bi	7440-69-9	▼	5	mg			363.46
							C	GROUP-C		CaO	1305-78-8	▼	151	mg			62,419
							C	GROUP-C		SiO2	7631-86-9	▼	352	mg			145,50
							C	GROUP-C		Brome compounds		▼	72	mg			29,763
							C	GROUP-C		MgO	1309-48-4	▼	38	mg			15,708

				C	GROUP-C		Al2O3	1344-28-1		95	mg			39,270
				C	GROUP-C		Sn	7440-31-5		56	mg			23,149
				B	Antimony/Antimony C		Sb2O3	1309-64-4		22	mg			1,599.2
Adhesive/ TIM	180	mg		C	GROUP-C		Others	Trade Secret		18	mg			99,999
				C	GROUP-C		Alumina	01344-28-1		162	mg			899,99
Bump	13.42	mg		A	Lead/Lead Compound		Pb	7439-92-1		6.8554	mg			510,83
				C	GROUP-C		Sn	7440-31-5		6.5646	mg			489,16
Heatslug	9,697	mg		C	GROUP-C		Chrome	-		4.8485	mg			500
				B	Nickel/Nickel Compou		Nickel	7440-02-0		58.182	mg			4,229.4
				C	GROUP-C		Copper	7440-50-8		9,633.96	mg			993,49